

APPROVAL DRAWING

Surge Components product name
SES5VSC70-6 TR (RoHS compliant)

CONTENTS

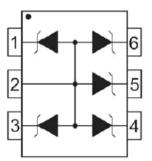
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	Surg	ge Components, Inc.
Customer Acknowledgement		Manufacturer Surge Components, Inc.
		2009-05-06



1.FEATURE

- 100 Watts Peak Power per Line(tp=8/20us)
- SC-70-6L package
- Protect 4 lines bidirectional and 5 lines unidirectional
- Monolithic structure
- Working woltage: 5V
- Low clamping voltage
- ESD protection > 15KV
- Low leakage current
- RoHS compliant
- Transient protection for data lines to IEC 61000-4-2(ESD) ± 15KV (air),
 - ± 8KV (contact); IEC 61000-4-4 (EFT) 40A (5/50ns)



2. APPLICATION

- Cellular phones
- MP3 players
- Notebook
- PDAs
- Digital cameras
- Cellular phones station

3. ELECTRICAL CHARACTERISTICS PER LINE@25℃(UNLESS OTHERWISE SPECIFIED)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Reverse stand-off voltage	V_{RWM}				5	V
Reverse Breakdown voltage	V_{BR}	I _t =1mA	6			V
Reverse Leakage Current	I _R	V _{RWM} =5V T=25°C			5	uA
Clamping Voltage	V _C	I _{PP} =1A T _P =8/20uS			8.8	V
Clamping voltage	V _C	I _{PP} =10A T _P =8/20uS			10.0	V
Junction Capacitance	CJ	V _R =0V f=1MHz		60		pF

Note 1: Pin 1,3,4,5 or 6 to Pin 2

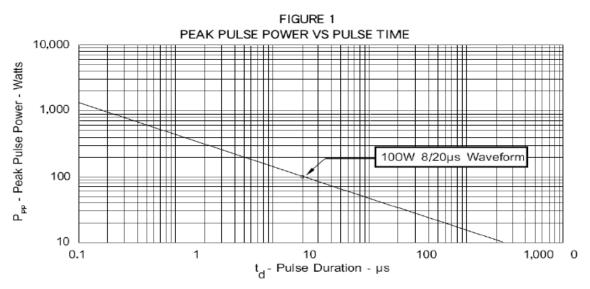


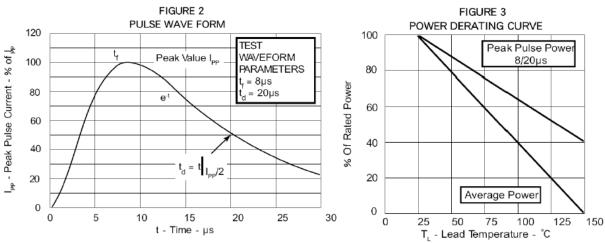
4. ABSOLUTE MAXIMUM RATING @25℃ NOTE 1

Rating	Symbol	Value	Units
Peak Pulse Power(t _p =8/20µs)	P _{PP}	100	W
Forward voltage@1A, 8/20µs	V _F	1.5	V
Operating Temperature	Tj	-55 to +150	$^{\circ}$ C
Storage Temperature	T _{STG}	-55 to +150	$^{\circ}$ C

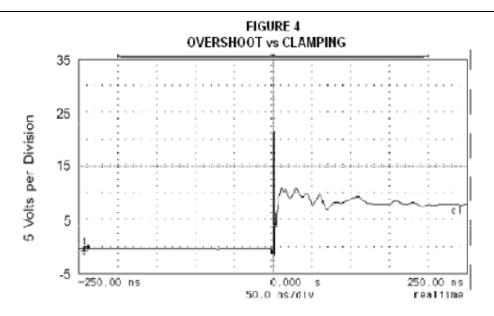
Note 1: Pin 1,3,4,5 or 6 to Pin 2

5.TYPICAL CHARACTERISTICS

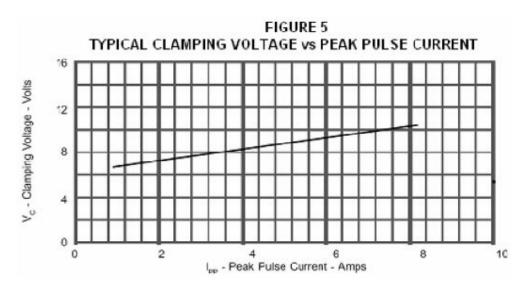




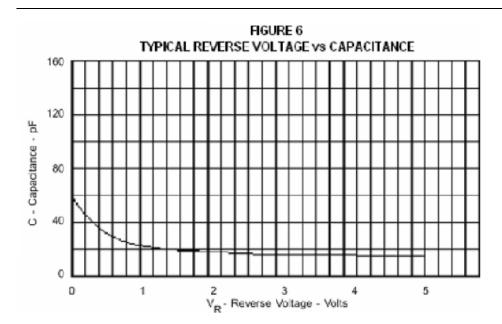




ESD Test Pulse: 5 kilovalt, 1/30ns (waveform)

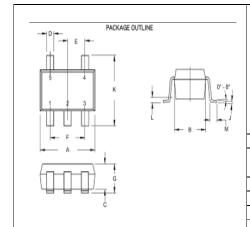








6. PRODUCT DIMENSION



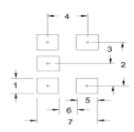
SC70-6L



PACKAGE OUTLINE									
DIM	MILIME:	TER	INCHES						
	MIN	MAX	MIN	MAX					
Α	1.90	2.15	0.075	0.085					
В	1.15	1.35	0.045	0.053					
С	0.80	1.00	0.031	0.039					
D	0.15	0.30	0.006	0.012					
Е	0.65 BSC	-	0.026 BSC	-					
F	1.30 BSC	-	0.051 BSC	-					
G	0.80	1.10	0.031	0.043					
J	0.08	0.25	0.003	0.010					
K	1.90	2.15	0.075	0.085					
L	0	0.10	0	0.004					
M	0.26	0.46	0.010	0.018					

MOUNTING PAD

	TYPICAL							
DIM	Millimeter	Inches						
1	0.50	0.020						
2	1.30	0.051						
3	0.65	0.026						
4	1.72	0.068						
5	0.60	0.024						
6	1.11	0.044						
7	2.33	0.092						



NOTES

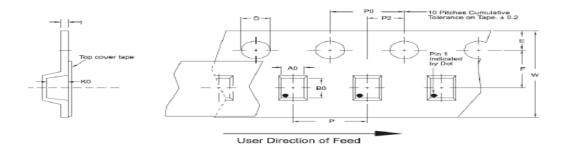
TAPE & REEL ORDERING NOMENCLATURE

- 1. Surface mount product is taped and reeled in accordance with EIA-481.
- 2. 7 Inch Reel 3,000 pieces per 8mm tape.



7. PACKING INFORMATION

Reel Dia	Tape Width	AO	ВО	КО	D	E	F	W	PO	P2	Р	lmax
178mm(7")	8mm	2.25±0.10	2.34±0.10	1.22±0.10	1.50±0.10	1.75±0.10	3.50±0.05	8.00±0.30	4.00±0.10	2.00±0.005	4.00±0.005	0.25



8. APPLICATION NOTE

The SES5VSC70-6 is TVS arrays designed to protect I/O or data lines from the damaging effects of ESD or EFT. This product provides both unidirectional and bidirectional protection, with a surage capability of 100 watts Ppp line for an 8/20µs wave shape and ESD protection > 25kv.

Common-mode unidirectional configuration (Figure 1)

The SES5VSC70-6 provides up to 5 lines of protection in a common-mode unidirectional configuration as depicted in Figure 1.

Circuit connectivity is as follows:

- Line 1 is connected to Pin1.
- Line 2 is connected to Pin3.
- Line 3 is connected to Pin4.
- Line 4 is connected to Pin6
- Line 5 is connected to Pin5.
- Pin2 is connected to ground.

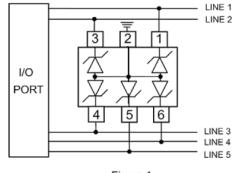


Figure 1



The SES5VSC70-6 provides up to 4 lines of protection in a common-mode bidirectional configuration as depicted in Figure 2.

Circuit connectivity is as follows:

- Line 1 is connected to Pin1.
- Line 2 is connected to Pin3.
- Line 3 is connected to Pin4
- Line 4 is connected to Pin6
- Pin5 is connected to ground.
- Pin2 is not connected.

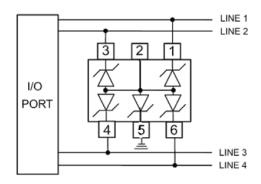


Figure 2

Differential-mode bidirectional configuration (Figure 3)

The SES5VSC70-5 provides up to 4 lines of protection in a differential-mode bidirectional configuration as depicted in Figure 3.

Circuit connectivity is as follows:

- Line 1 is connected to Pin1.
- Line 2 is connected to Pin3.
- Line 3 is connected to Pin4.
- Line 4 is connected to Pin6.
- Line 5 is connected to Pin5.
- Pin2 is not connected.

I/O PORT 4 5 6 LINE 3 LINE 4 LINE 5

Figure 3

Circuit board layout and protection device placement:

Circuit board layout is critical for suppression of ESD transients.

The following guidelines are recommended:

- 1. Place the protection devices as close to the input terminal or connector as possible.
- 2. The path length between the protection device and protected line should be minimized.
- 3. Keep parallel signal pats to a minimum.
- 4. Avoid running protection conductors in parallel with unprotected conductor.
- 5. Minimize all printed-circuit board conductive loops including power and ground loops.
- 6. minimize the length of the transient return path to ground.
- 7. Avoid using shared transient return paths to common ground point.
- 8. Ground planes should be used whenever possible. For multilayer printed-circuit boards, use ground vias